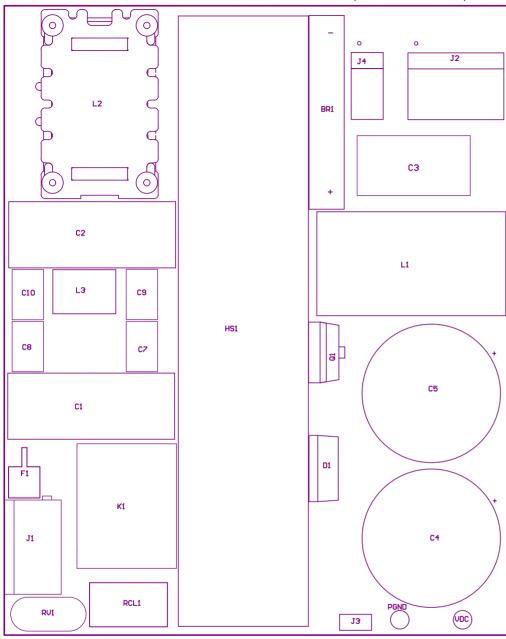
ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZI Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

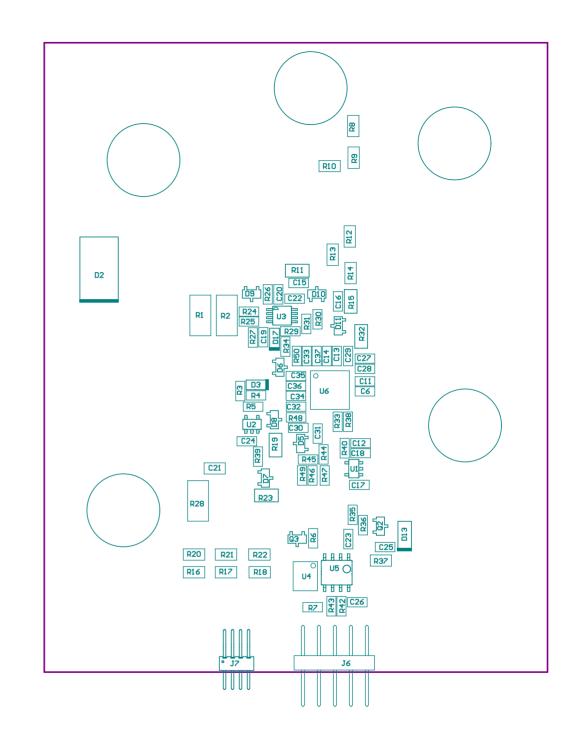


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT:

[No Variations]

PCB VIEWED FROM TOP SIDE		BOARD #:	TIDA-00707	REU: E1	SVN REV:	Not In VersionControl
	M5 Assembly Top	TID #:	TIDA-00707			
PLOT NAME =	Top Assembly Drawing	GENERATED :	3/17/2016	1:46:10 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #:	TIDA-00707	REV: E1	SUN REV:	Not In VersionControl
M6 Assembly Bottom	TID #:	TIDA-00707			
PLOT NAME = Bottom Assembly Drawing	GENERATED :	3/17/2016	1:46:10 PM		TEXAS INSTRUMENTS

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